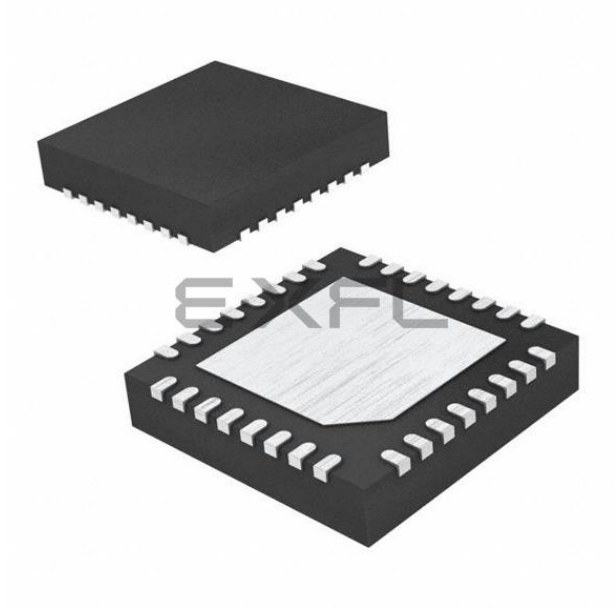
Microchip Technology - DSPIC33EP32GS502-I/2N Datasheet



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	21
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 12x12b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-UQFN Exposed Pad
Supplier Device Package	28-UQFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep32gs502-i-2n

TABLE 1-1: PINOUT I/O DESCRIPTIONS

Pin Name(1)	Pin Type	Buffer Type	PPS	Description
AN0-AN21	I	Analog	No	Analog input channels.
AN0ALT-AN1ALT	I	Analog	No	Alternate analog input channels.
CLKI	I	ST/ CMOS	No	External clock source input. Always associated with OSC1 pin function.
CLKO	O	—	No	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes. Always associated with OSC2 pin function.
OSC1	I	ST/ CMOS	No	Oscillator crystal input. ST buffer when configured in RC mode; CMOS otherwise.
OSC2	I/O	—	No	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. Optionally functions as CLKO in RC and EC modes.
REFCLKO	O	—	Yes	Reference clock output.
IC1-IC4	I	ST	Yes	Capture Inputs 1 through 4.
OCFA	I	ST	Yes	Compare Fault A input (for compare channels).
OC1-OC4	O	—	Yes	Compare Outputs 1 through 4.
INT0	I	ST	No	External Interrupt 0.
INT1	I	ST	Yes	External Interrupt 1.
INT2	I	ST	Yes	External Interrupt 2.
INT4	I	ST	No	External Interrupt 4.
RA0-RA4	I/O	ST	No	PORTA is a bidirectional I/O port.
RB0-RB15	I/O	ST	No	PORTB is a bidirectional I/O port.
RC0-RC15	I/O	ST	No	PORTC is a bidirectional I/O port.
RD0-RD15	I/O	ST	No	PORTD is a bidirectional I/O port.
T1CK	I	ST	Yes	Timer1 external clock input.
T2CK	I	ST	Yes	Timer2 external clock input.
T3CK	I	ST	Yes	Timer3 external clock input.
T4CK	I	ST	No	Timer4 external clock input.
T5CK	I	ST	No	Timer5 external clock input.
$\overline{U1CTS}$	I	ST	Yes	UART1 Clear-to-Send.
$\overline{U1RTS}$	O	—	Yes	UART1 Request-to-Send.
U1RX	I	ST	Yes	UART1 receive.
U1TX	O	—	Yes	UART1 transmit.
BCLK1	O	ST	Yes	UART1 IrDA® baud clock output.
$\overline{U2CTS}$	I	ST	Yes	UART2 Clear-to-Send.
$\overline{U2RTS}$	O	—	Yes	UART2 Request-to-Send.
U2RX	I	ST	Yes	UART2 receive.
U2TX	O	—	Yes	UART2 transmit.
BCLK2	O	ST	Yes	UART2 IrDA baud clock output.
SCK1	I/O	ST	Yes	Synchronous serial clock input/output for SPI1.
SDI1	I	ST	Yes	SPI1 data in.
$\overline{SDO1}$	O	—	Yes	SPI1 data out.
$\overline{SS1}$	I/O	ST	Yes	SPI1 slave synchronization or frame pulse I/O.
SCK2	I/O	ST	Yes	Synchronous serial clock input/output for SPI2.
SDI2	I	ST	Yes	SPI2 data in.
$\overline{SDO2}$	O	—	Yes	SPI2 data out.
$\overline{SS2}$	I/O	ST	Yes	SPI2 slave synchronization or frame pulse I/O.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
PPS = Peripheral Pin Select; TTL = TTL input buffer

1: Not all pins are available in all packages variants. See the **"Pin Diagrams"** section for pin availability.

2: These pins are dedicated on 64-pin devices.

2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT DIGITAL SIGNAL CONTROLLERS

Note 1: This data sheet summarizes the features of the dsPIC33EPXXGS50X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

2.1 Basic Connection Requirements

Getting started with the dsPIC33EPXXGS50X family requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names which must always be connected:

- All VDD and VSS pins
  (see **Section 2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins
  regardless if ADC module is not used (see **Section 2.2 "Decoupling Capacitors"**)
- VCAP
  (see **Section 2.3 "CPU Logic Filter Capacitor Connection (VCAP)"**)
- $\overline{\text{MCLR}}$ pin
  (see **Section 2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins
  used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see **Section 2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins
  when external oscillator source is used (see **Section 2.6 "External Oscillator Pins"**)

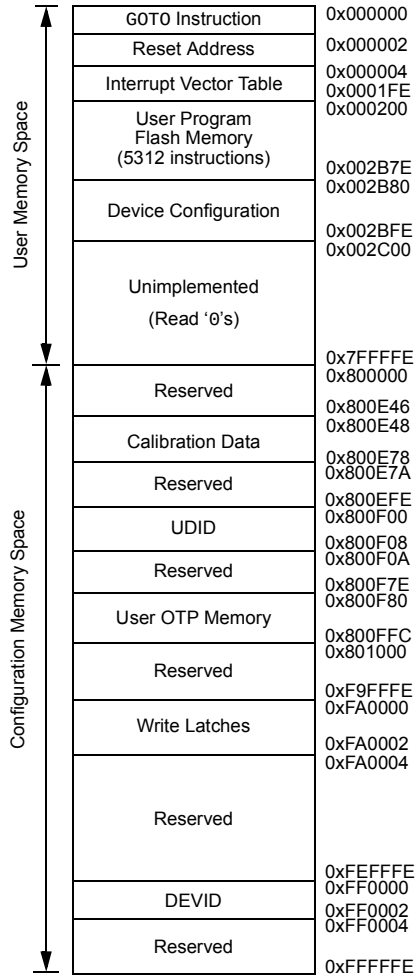
2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS is required.

Consider the following criteria when using decoupling capacitors:

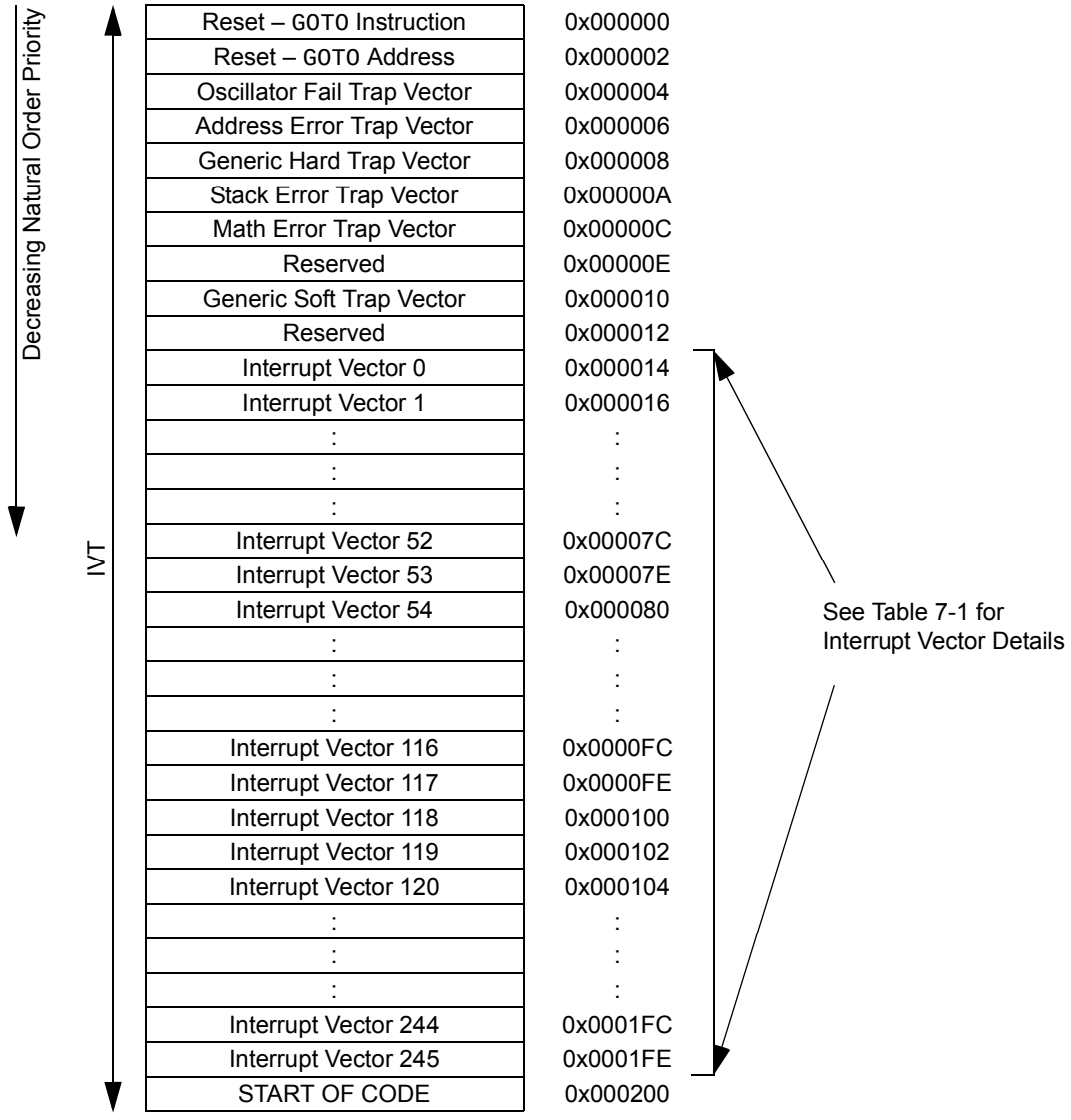
- **Value and type of capacitor:** Recommendation of 0.1 µF (100 nF), 10-20V. This capacitor should be a low-ESR and have resonance frequency in the range of 20 MHz and higher. It is recommended to use ceramic capacitors.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise, above tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB track inductance.

FIGURE 4-1: PROGRAM MEMORY MAP FOR dsPIC33EP16GS50X DEVICES



Note: Memory areas are not shown to scale.

FIGURE 7-1: dsPIC33EPXXGS50X FAMILY INTERRUPT VECTOR TABLE



Note: In Dual Partition modes, each partition has a dedicated Interrupt Vector Table.

REGISTER 7-3: INTCON1: INTERRUPT CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NSTDIS	OVAERR	OVBERR	COVAERR	COVBERR	OVATE	OVBTE	COVTE
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0
SFTACERR	DIV0ERR	—	MATHERR	ADDRERR	STKERR	OSCFAIL	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **NSTDIS:** Interrupt Nesting Disable bit
1 = Interrupt nesting is disabled
0 = Interrupt nesting is enabled

bit 14 **OVAERR:** Accumulator A Overflow Trap Flag bit
1 = Trap was caused by overflow of Accumulator A
0 = Trap was not caused by overflow of Accumulator A

bit 13 **OVBERR:** Accumulator B Overflow Trap Flag bit
1 = Trap was caused by overflow of Accumulator B
0 = Trap was not caused by overflow of Accumulator B

bit 12 **COVAERR:** Accumulator A Catastrophic Overflow Trap Flag bit
1 = Trap was caused by catastrophic overflow of Accumulator A
0 = Trap was not caused by catastrophic overflow of Accumulator A

bit 11 **COVBERR:** Accumulator B Catastrophic Overflow Trap Flag bit
1 = Trap was caused by catastrophic overflow of Accumulator B
0 = Trap was not caused by catastrophic overflow of Accumulator B

bit 10 **OVATE:** Accumulator A Overflow Trap Enable bit
1 = Trap overflow of Accumulator A
0 = Trap is disabled

bit 9 **OVBTE:** Accumulator B Overflow Trap Enable bit
1 = Trap overflow of Accumulator B
0 = Trap is disabled

bit 8 **COVTE:** Catastrophic Overflow Trap Enable bit
1 = Trap on catastrophic overflow of Accumulator A or B is enabled
0 = Trap is disabled

bit 7 **SFTACERR:** Shift Accumulator Error Status bit
1 = Math error trap was caused by an invalid accumulator shift
0 = Math error trap was not caused by an invalid accumulator shift

bit 6 **DIV0ERR:** Divide-by-Zero Error Status bit
1 = Math error trap was caused by a divide-by-zero
0 = Math error trap was not caused by a divide-by-zero

bit 5 **Unimplemented:** Read as ‘0’

bit 4 **MATHERR:** Math Error Status bit
1 = Math error trap has occurred
0 = Math error trap has not occurred

bit 3 **ADDRERR:** Address Error Trap Status bit
1 = Address error trap has occurred
0 = Address error trap has not occurred

TABLE 10-2: OUTPUT SELECTION FOR REMAPPABLE PINS (RPn)

Function	RPnR<5:0>	Output Name
Default PORT	000000	RPn tied to Default Pin
U1TX	000001	RPn tied to UART1 Transmit
$\overline{U1RTS}$	000010	RPn tied to UART1 Request-to-Send
U2TX	000011	RPn tied to UART2 Transmit
$\overline{U2RTS}$	000100	RPn tied to UART2 Request-to-Send
SDO1	000101	RPn tied to SPI1 Data Output
SCK1	000110	RPn tied to SPI1 Clock Output
$\overline{SS1}$	000111	RPn tied to SPI1 Slave Select
SDO2	001000	RPn tied to SPI2 Data Output
SCK2	001001	RPn tied to SPI2 Clock Output
$\overline{SS2}$	001010	RPn tied to SPI2 Slave Select
OC1	010000	RPn tied to Output Compare 1 Output
OC2	010001	RPn tied to Output Compare 2 Output
OC3	010010	RPn tied to Output Compare 3 Output
OC4	010011	RPn tied to Output Compare 4 Output
ACMP1	011000	RPn tied to Analog Comparator 1 Output
ACMP2	011001	RPn tied to Analog Comparator 2 Output
ACMP3	011010	RPn tied to Analog Comparator 3 Output
SYNCO1	101101	RPn tied to PWM Primary Master Time Base Sync Output
SYNCO2	101110	RPn tied to PWM Secondary Master Time Base Sync Output
REFCLKO	110001	RPn tied to Reference Clock Output
ACMP4	110010	RPn tied to Analog Comparator 4 Output
PWM4H	110011	RPn tied to PWM Output Pins Associated with PWM Generator 4
PWM4L	110100	RPn tied to PWM Output Pins Associated with PWM Generator 4
PWM5H	110101	RPn tied to PWM Output Pins Associated with PWM Generator 5
PWM5L	110110	RPn tied to PWM Output Pins Associated with PWM Generator 5

11.0 TIMER1

Note 1: This data sheet summarizes the features of the dsPIC33EPXXGS50X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Timers"** (DS70362) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Timer1 module is a 16-bit timer that can operate as a free-running interval timer/counter.

The Timer1 module has the following unique features over other timers:

- Can be Operated in Asynchronous Counter mode from an External Clock Source
- The External Clock Input (T1CK) can Optionally be Synchronized to the Internal Device Clock and the Clock Synchronization is Performed after the Prescaler

A block diagram of Timer1 is shown in Figure 11-1.

The Timer1 module can operate in one of the following modes:

- Timer mode
- Gated Timer mode
- Synchronous Counter mode
- Asynchronous Counter mode

In Timer and Gated Timer modes, the input clock is derived from the internal instruction cycle clock (FCY). In Synchronous and Asynchronous Counter modes, the input clock is derived from the external clock input at the T1CK pin.

The Timer modes are determined by the following bits:

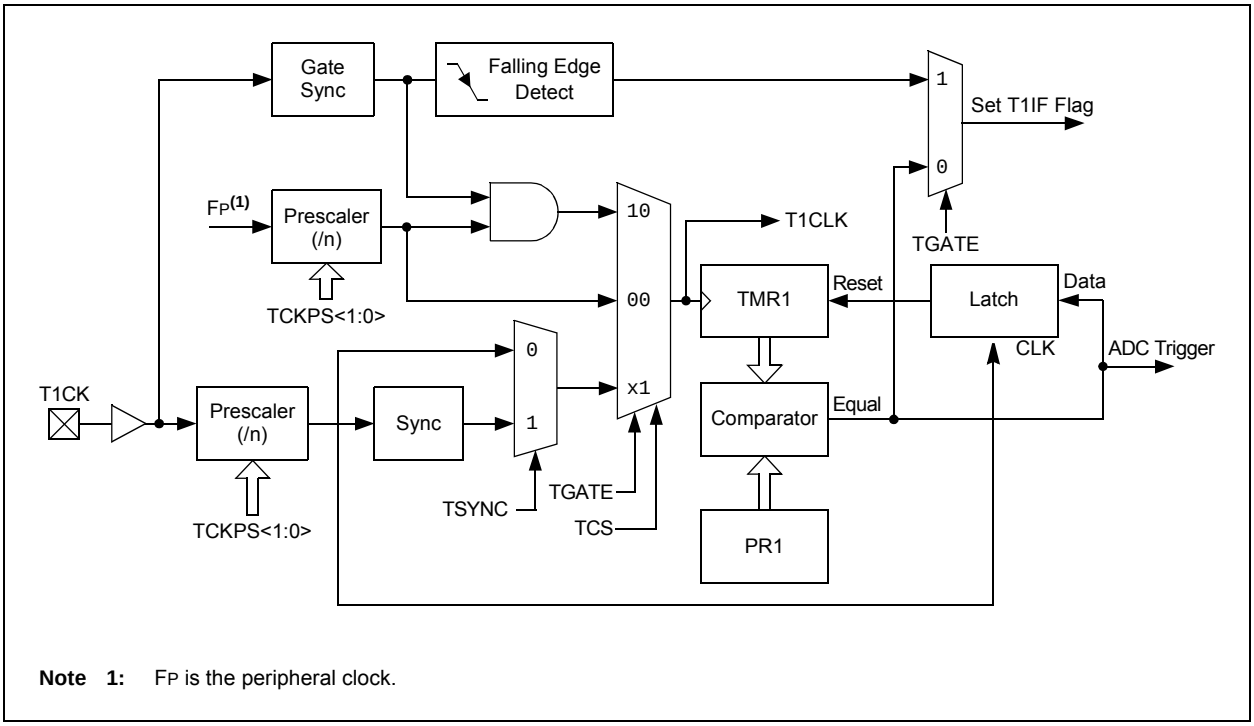
- Timer Clock Source Control bit (TCS): T1CON<1>
- Timer Synchronization Control bit (TSYNC): T1CON<2>
- Timer Gate Control bit (TGATE): T1CON<6>

Timer control bit settings for different operating modes are provided in Table 11-1.

TABLE 11-1: TIMER MODE SETTINGS

Mode	TCS	TGATE	TSYNC
Timer	0	0	x
Gated Timer	0	1	x
Synchronous Counter	1	x	1
Asynchronous Counter	1	x	0

FIGURE 11-1: 16-BIT TIMER1 MODULE BLOCK DIAGRAM



Note 1: FP is the peripheral clock.

REGISTER 15-12: PWMCONx: PWMx CONTROL REGISTER (x = 1 to 5)

R-0, HSC	R-0, HSC	R-0, HSC	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
FLTSTAT(1)	CLSTAT(1)	TRGSTAT	FLTIEN	CLIEN	TRGIEN	ITB(3)	MDCS(3)
bit 15							bit 8

R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
DTC1	DTC0	—	—	MTBS	CAM(2,3,4)	XPRES(5)	IUE
bit 7							bit 0

Legend:	HSC = Hardware Settable/Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **FLTSTAT:** Fault Interrupt Status bit(1)
- 1 = Fault interrupt is pending
- 0 = No Fault interrupt is pending
- This bit is cleared by setting FLTIEN = 0.

bit 14 **CLSTAT:** Current-Limit Interrupt Status bit(1)
- 1 = Current-limit interrupt is pending
- 0 = No current-limit interrupt is pending
- This bit is cleared by setting CLIEN = 0.

bit 13 **TRGSTAT:** Trigger Interrupt Status bit
- 1 = Trigger interrupt is pending
- 0 = No trigger interrupt is pending
- This bit is cleared by setting TRGIEN = 0.

bit 12 **FLTIEN:** Fault Interrupt Enable bit
- 1 = Fault interrupt is enabled
- 0 = Fault interrupt is disabled and the FLTSTAT bit is cleared

bit 11 **CLIEN:** Current-Limit Interrupt Enable bit
- 1 = Current-limit interrupt is enabled
- 0 = Current-limit interrupt is disabled and the CLSTAT bit is cleared

bit 10 **TRGIEN:** Trigger Interrupt Enable bit
- 1 = A trigger event generates an interrupt request
- 0 = Trigger event interrupts are disabled and the TRGSTAT bit is cleared

bit 9 **ITB:** Independent Time Base Mode bit(3)
- 1 = PHASEx/SPHASEx registers provide the time base period for this PWMx generator
- 0 = PTPER register provides timing for this PWMx generator

bit 8 **MDCS:** Master Duty Cycle Register Select bit(3)
- 1 = MDC register provides duty cycle information for this PWMx generator
- 0 = PDCx and SDCx registers provide duty cycle information for this PWMx generator

Note 1: Software must clear the interrupt status here and in the corresponding IFSx bit in the interrupt controller.

2: The Independent Time Base mode (ITB = 1) must be enabled to use Center-Aligned mode. If ITB = 0, the CAM bit is ignored.

3: These bits should not be changed after the PWMx is enabled by setting PTEN = 1 (PTCON<15>).

4: Center-Aligned mode ignores the Least Significant 3 bits of the Duty Cycle, Phase and Dead-Time registers. The highest Center-Aligned mode resolution available is 8.32 ns with the clock prescaler set to the fastest clock.

5: Configure CLMOD = 0 (FCLCONx<8>) and ITB = 1 (PWMCONx<9>) to operate in External Period Reset mode.

REGISTER 16-2: SPIxCON1: SPIx CONTROL REGISTER 1

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	DISSCK	DISSDO	MODE16	SMP	CKE(1)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SSEN(2)	CKP	MSTEN	SPRE2(3)	SPRE1(3)	SPRE0(3)	PPRE1(3)	PPRE0(3)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12 **DISSCK:** Disable SCKx Pin bit (SPIx Master modes only)
1 = Internal SPIx clock is disabled, pin functions as I/O
0 = Internal SPIx clock is enabled

bit 11 **DISSDO:** Disable SDOx Pin bit
1 = SDOx pin is not used by the module; pin functions as I/O
0 = SDOx pin is controlled by the module

bit 10 **MODE16:** Word/Byte Communication Select bit
1 = Communication is word-wide (16 bits)
0 = Communication is byte-wide (8 bits)

bit 9 **SMP:** SPIx Data Input Sample Phase bit
Master Mode:
1 = Input data is sampled at the end of data output time
0 = Input data is sampled at the middle of data output time
Slave Mode:
SMP must be cleared when SPIx is used in Slave mode.

bit 8 **CKE:** SPIx Clock Edge Select bit(1)
1 = Serial output data changes on transition from active clock state to Idle clock state (refer to bit 6)
0 = Serial output data changes on transition from Idle clock state to active clock state (refer to bit 6)

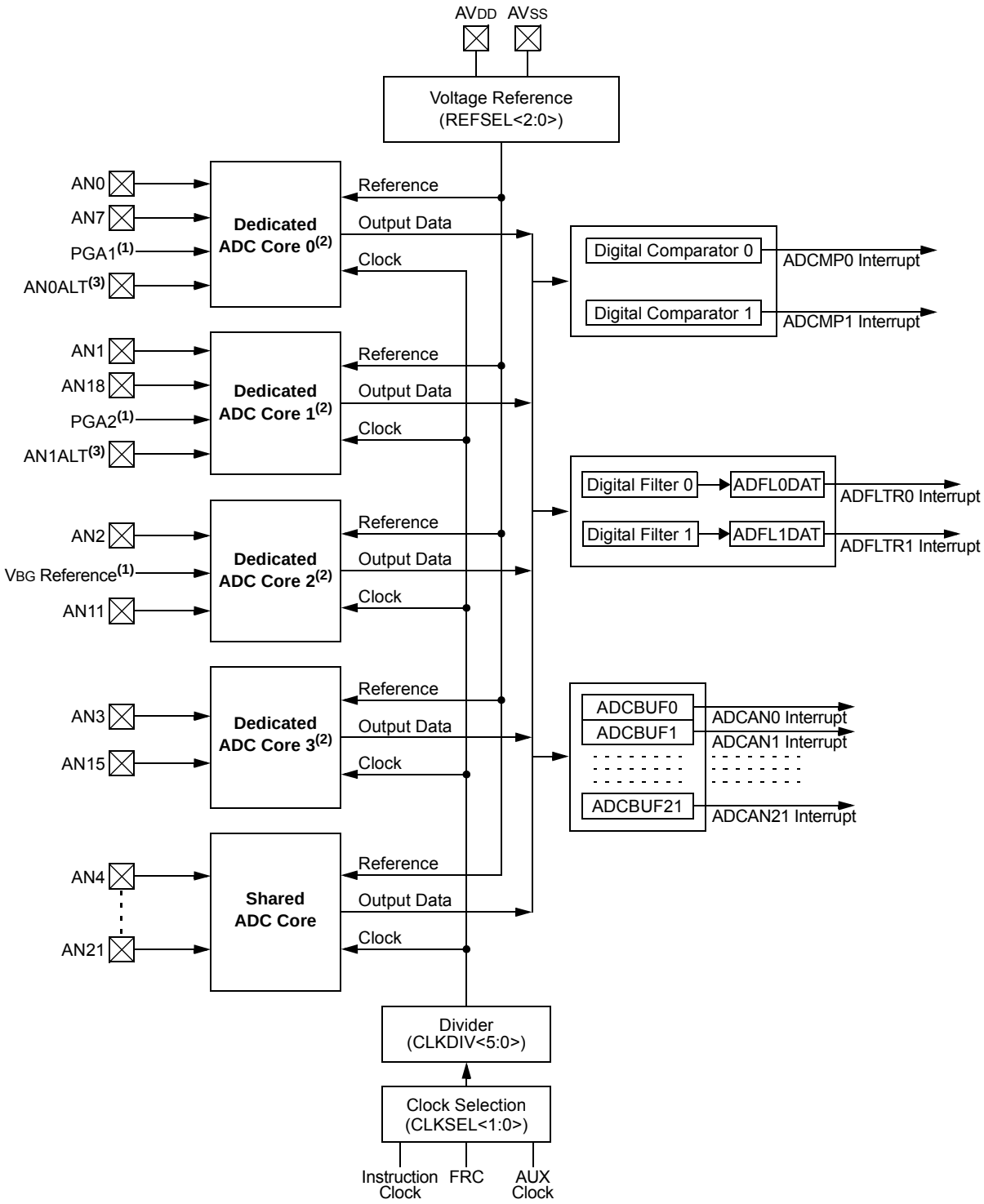
bit 7 **SSEN:** Slave Select Enable bit (Slave mode)(2)
1 = $\overline{SSx}$ pin is used for Slave mode
0 = $\overline{SSx}$ pin is not used by the module; pin is controlled by port function

bit 6 **CKP:** Clock Polarity Select bit
1 = Idle state for clock is a high level; active state is a low level
0 = Idle state for clock is a low level; active state is a high level

bit 5 **MSTEN:** Master Mode Enable bit
1 = Master mode
0 = Slave mode

Note 1: The CKE bit is not used in Framed SPI modes. Program this bit to '0' for Framed SPI modes (FRMEN = 1).
2: This bit must be cleared when FRMEN = 1.
3: Do not set both primary and secondary prescalers to the value of 1:1.

FIGURE 19-1: ADC MODULE BLOCK DIAGRAM



Note 1: PGA1, PGA2 and Band Gap Reference (V_{BG}) are internal analog inputs and are not available on device pins.
2: If the dedicated core uses an alternate channel, then shared core function cannot be used.
3: AN0ALT and AN1ALT are not available on dsPIC33EPXXGS502 devices.

REGISTER 19-3: ADCON2L: ADC CONTROL REGISTER 2 LOW

R/W-0	R/W-0	r-0	R/W-0	r-0	R/W-0	R/W-0	R/W-0
REFCIE	REFERCIE	—	EIEN	—	SHREISEL2(1)	SHREISEL1(1)	SHREISEL0(1)
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	SHRADCS6	SHRADCS5	SHRADCS4	SHRADCS3	SHRADCS2	SHRADCS1	SHRADCS0
bit 7							bit 0

Legend:	r = Reserved bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **REFCIE:** Band Gap and Reference Voltage Ready Common Interrupt Enable bit
1 = Common interrupt will be generated when the band gap will become ready
0 = Common interrupt is disabled for the band gap ready event

bit 14 **REFERCIE:** Band Gap or Reference Voltage Error Common Interrupt Enable bit
1 = Common interrupt will be generated when a band gap or reference voltage error is detected
0 = Common interrupt is disabled for the band gap and reference voltage error event

bit 13 **Reserved:** Maintain as '0'

bit 12 **EIEN:** Early Interrupts Enable bit
1 = The early interrupt feature is enabled for the input channel interrupts (when the EISTATx flag is set)
0 = The individual interrupts are generated when conversion is done (when the ANxRDY flag is set)

bit 11 **Reserved:** Maintain as '0'

bit 10-8 **SHREISEL<2:0>:** Shared Core Early Interrupt Time Selection bits(1)
111 = Early interrupt is set and interrupt is generated 8 TADCORE clocks prior to when the data is ready
110 = Early interrupt is set and interrupt is generated 7 TADCORE clocks prior to when the data is ready
101 = Early interrupt is set and interrupt is generated 6 TADCORE clocks prior to when the data is ready
100 = Early interrupt is set and interrupt is generated 5 TADCORE clocks prior to when the data is ready
011 = Early interrupt is set and interrupt is generated 4 TADCORE clocks prior to when the data is ready
010 = Early interrupt is set and interrupt is generated 3 TADCORE clocks prior to when the data is ready
001 = Early interrupt is set and interrupt is generated 2 TADCORE clocks prior to when the data is ready
000 = Early interrupt is set and interrupt is generated 1 TADCORE clock prior to when the data is ready

bit 7 **Unimplemented:** Read as '0'

bit 6-0 **SHRADCS<6:0>:** Shared ADC Core Input Clock Divider bits
These bits determine the number of TCORESRC (Source Clock Periods) for one shared TADCORE (Core Clock Period).
1111111 = 254 Source Clock Periods
•
•
•
0000011 = 6 Source Clock Periods
0000010 = 4 Source Clock Periods
0000001 = 2 Source Clock Periods
0000000 = 2 Source Clock Periods

Note 1: For the 6-bit shared ADC core resolution (SHRRES<1:0> = 00), the SHREISEL<2:0> settings, from '100' to '111', are not valid and should not be used. For the 8-bit shared ADC core resolution (SHRRES<1:0> = 01), the SHREISEL<2:0> settings, '110' and '111', are not valid and should not be used.

REGISTER 19-27: ADTRIGxH: ADC CHANNEL TRIGGER x SELECTION REGISTER HIGH (x = 0 to 5) (CONTINUED)

bit 4-0 **TRGSRC(4x+2)<4:0>:** Trigger Source Selection for Corresponding Analog Inputs bits

11111 = ADTRG31
11110 = Reserved
11101 = Reserved
11100 = PWM Generator 5 current-limit trigger
11011 = PWM Generator 4 current-limit trigger
11010 = PWM Generator 3 current-limit trigger
11001 = PWM Generator 2 current-limit trigger
11000 = PWM Generator 1 current-limit trigger
10111 = Output Compare 2 trigger
10110 = Output Compare 1 trigger
10101 = Reserved
10100 = Reserved
10011 = PWM Generator 5 secondary trigger
10010 = PWM Generator 4 secondary trigger
10001 = PWM Generator 3 secondary trigger
10000 = PWM Generator 2 secondary trigger
01111 = PWM Generator 1 secondary trigger
01110 = PWM secondary Special Event Trigger
01101 = Timer2 period match
01100 = Timer1 period match
01011 = Reserved
01010 = Reserved
01001 = PWM Generator 5 primary trigger
01000 = PWM Generator 4 primary trigger
00111 = PWM Generator 3 primary trigger
00110 = PWM Generator 2 primary trigger
00101 = PWM Generator 1 primary trigger
00100 = PWM Special Event Trigger
00011 = Reserved
00010 = Level software trigger
00001 = Common software trigger
00000 = No trigger is enabled

REGISTER 19-34: ADFLxCON: ADC DIGITAL FILTER x CONTROL REGISTER (x = 0 or 1) (CONTINUED)

bit 4-0 **FLCHSEL<4:0>:** Oversampling Filter Input Channel Selection bits

11111 = Reserved
•
•
•
10110 = Reserved
10101 = AN21
10100 = AN20
•
•
•
00001 = AN1
00000 = AN0

TABLE 26-8: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Parameter No.	**Typ.**	**Max.**	**Units**	**Conditions**	
Power-Down Current (I_{PD})(1)					
DC60d	12	100	μA	-40°C	3.3V
DC60a	18	100	μA	+25°C	
DC60b	130	400	μA	+85°C	
DC60c	500	1100	μA	+125°C	

Note 1: I_{PD} (Sleep) current is measured as follows:

- CPU core is off, oscillator is configured in EC mode and external clock is active; OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{MCLR}$ = VDD, WDT and FSCM are disabled
- All peripheral modules are disabled (PMDx bits are all set)
- The VREGS bit (RCON<8>) = 0 (i.e., core regulator is set to standby while the device is in Sleep mode)
- The VREGSF bit (RCON<11>) = 0 (i.e., Flash regulator is set to standby while the device is in Sleep mode)
- JTAG is disabled

TABLE 26-9: DC CHARACTERISTICS: WATCHDOG TIMER DELTA CURRENT (ΔI_{WDT})(1)

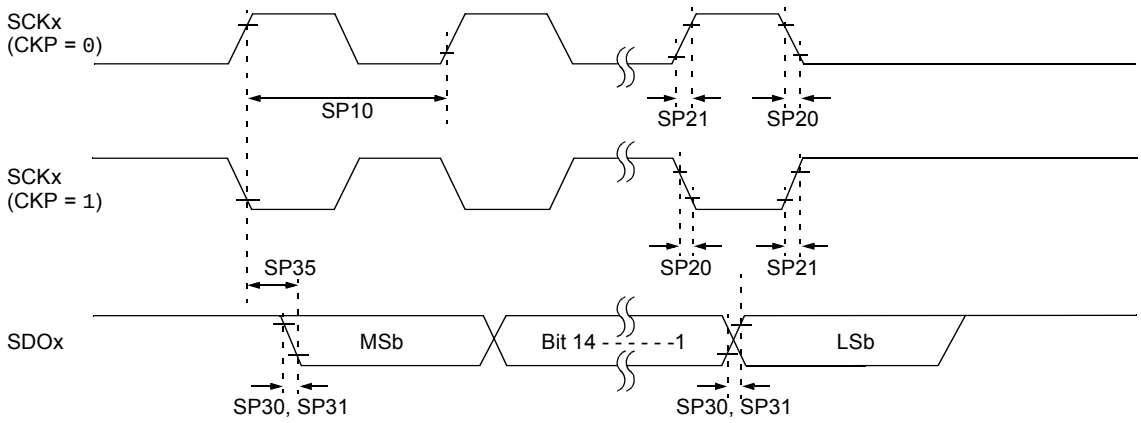
DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Parameter No.	**Typ.**	**Max.**	**Units**	**Conditions**	
DC61d	13	50	μA	-40°C	3.3V
DC61a	19	80	μA	+25°C	
DC61b	12	—	μA	+85°C	
DC61c	13	—	μA	+125°C	

Note 1: The ΔI_{WDT} current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current. All parameters are characterized but not tested during manufacturing.

TABLE 26-31: SPIx MAXIMUM DATA/CLOCK RATE SUMMARY

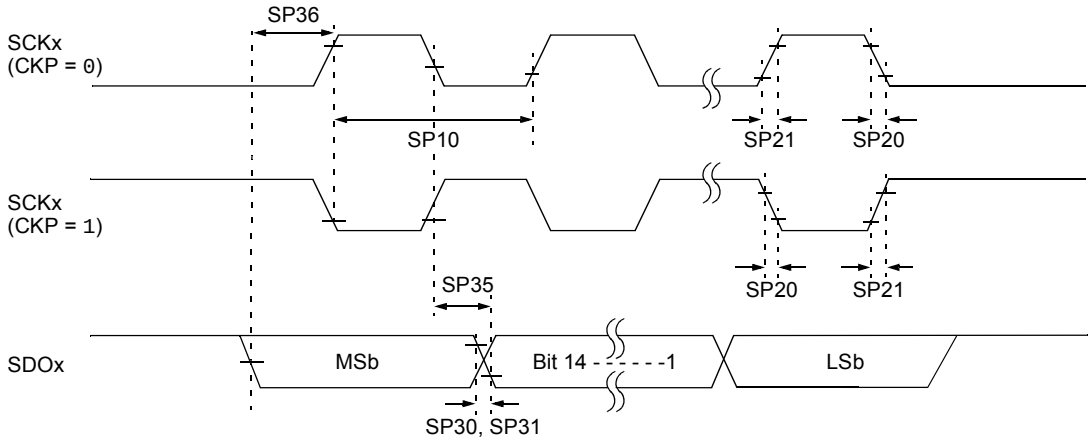
AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Maximum Data Rate	**Master Transmit Only (Half-Duplex)**	**Master Transmit/Receive (Full-Duplex)**	**Slave Transmit/Receive (Full-Duplex)**	**CKE**	**CKP**	**SMP**
15 MHz	Table 26-31	—	—	0,1	0,1	0,1
9 MHz	—	Table 26-32	—	1	0,1	1
9 MHz	—	Table 26-33	—	0	0,1	1
15 MHz	—	—	Table 26-34	1	0	0
11 MHz	—	—	Table 26-35	1	1	0
15 MHz	—	—	Table 26-36	0	1	0
11 MHz	—	—	Table 26-37	0	0	0

FIGURE 26-11: SPIx MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 26-1 for load conditions.

FIGURE 26-12: SPIx MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 26-1 for load conditions.

TABLE 26-32: SPIx MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCKx Frequency	—	—	15	MHz	**(Note 3)**
SP20	TscF	SCKx Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP21	TscR	SCKx Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid After SCKx Edge	—	6	20	ns	
SP36	TdiV2scH, TdiV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ." column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 66.7 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

TABLE 26-37: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCKx Input Frequency	—	—	15	MHz	**(Note 3)**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid After SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↑ or SCKx ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance	10	—	50	ns	**(Note 4)**
SP52	TscH2ssH, TscL2ssH	$\overline{SSx}$ ↑ After SCKx Edge	1.5 TCY + 40	—	—	ns	**(Note 4)**

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ." column is at 3.3V, +25°C unless otherwise stated.

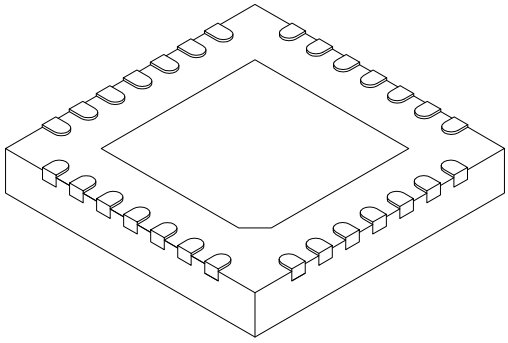
3: The minimum clock period for SCKx is 66.7 ns. Therefore, the SCKx clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

NOTES:

28-Lead Plastic Quad Flat, No Lead Package (MM) - 6x6x0.9mm Body [QFN-S]
With 0.40 mm Terminal Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.20 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	3.65	3.70	4.70
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	3.65	3.70	4.70
Terminal Width	b	0.23	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-124C Sheet 2 of 2

NOTES: